PCB SPECIFICATION 26.9.2005

PCB SPECIFICATION  Bluegiga Technologies Inc.				26.9.2005
PCB name	WT11EK Ver 1.0			
Board dimensions	94.94 mm X 75.02 mn	n		
Shape	Rectangular			
Panel:	306.66 mm x 170.42 r	nm		
Boards / Panel:	6 pcs	Shift X:	96,40 mm Shift	t Y: 76,48 mm
Material	FR-4, UL 94V-0			
Thickness	Other: Tol. +- 10% Se	e Drill drawi	ng	
Final copper thickness	Outer layers 35 µm	Inner laye	ers 35 µm	
Layers	4			
SMD component placement:	Top side only			
Manufacturing standards	-			
E				
Minimum conductor width	Outer layers 0.30 mm	•		
Minimum conductor spacing	Outer layers 0.15 mm Inner layers 0.15 mm			
Minimum annular ring	Outer layers * 0.15 mr	m Inner laye	rs * 0.15 mm	_
Minimum component pitch	0.5 mm			
Total No. SMD Pads/PCB	Top side 272 per	Dottom	ido O noo	
	Top side 372 pcs	Bottom s	ide o pos	_
Total No. Holes/PCB	844 pcs	-ll -l' 0 (	25	
Drill sizes	13 pcs Min. fini	shed dia. 0.2	25 mm	
Surface finishing				
Conductor plating	Copper			
Pad/land pattern coating	Immersion Gold (NiAu	ι)		
Solder resist (Green)	Liquid photo imageable			
	Top side: yes	Bottom s	ide: yes	
Temporary solder mask	No			
Silkscreen (White)	Top side: yes	Bottom s	ide: no	
Markings (On solder resist)	Manufacturer , Manufa	acturing Wee	ek and Year	
maninge (en eelde reelei)	UL-796 , Flammability	•	on and roa.	
Othe	•	olado		
Testing	Single Side 100% Ele	ctrical testing	g	
Additional Information				
Note: Special buil up, core 0.4 pad 0.5 mm, drill 0.3 mm; m		m ( see Drill	drawing picture )	
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Specification approved:				
Customer:		_		
N. I. a. a. a. a.				

Name:\_\_\_\_\_\_
Date:\_\_\_\_\_